


Full Material Declaration for attached parts list

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|  | <p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -</p> |
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Declaration effective from: 01 January 2010 [Approved on 03 February 2026, 11:28 GMT]

Materials and substances

| Use/Location | Material Group | % w/w of material in the part | Substances in the material | CAS Number | % w/w of substance in the material |
|---------------|---|-------------------------------|---|------------|------------------------------------|
| Chip (die) | Other inorganic materials | 0.93% | Silicon | 7440-21-3 | 100% |
| Die attach | Lead and Lead alloys | 3.27% | Silver | 7440-22-4 | 2.5% |
| | | | Tin | 7440-31-5 | 5% |
| | | | Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements | 7439-92-1 | 92.5% |
| Encapsulation | EP (Epoxy resin) | 44.09% | Carbon black | 1333-86-4 | 0.5% |
| | | | Magnesium hydroxide (Mg(OH) ₂) | 1309-42-8 | 3% |
| | | | Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol | 29690-82-2 | 7.5% |
| | | | Phenol, polymer with formaldehyde | 9003-35-4 | 13% |
| | | | Quartz (SiO₂) Exempt from other regulatory requirements | 14808-60-7 | 76% |
| Leadfinish | Tin plating | 0.3% | Tin | 7440-31-5 | 100% |
| Leadframe | Copper (e.g. copper amounts in cable harnesses) | 51.41% | Copper | 7440-50-8 | 100% |

Attached parts list

| Part number | Part name | Part Mass | Part Mass UoM |
|--------------------------|-----------|-----------|---------------|
| DO-214AB/SMC_(DJ)_H-free | Diode SMD | 0.2645 | g |
